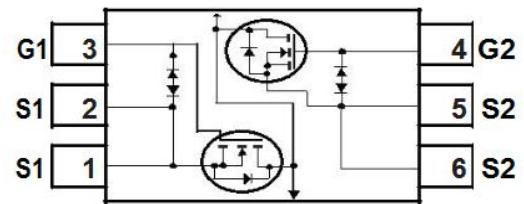




Dual N-Channel Enhancement Mode Power MOSFET

Description

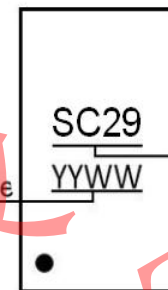
The MXN2384 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications. It is ESD protected.



Schematic diagram

General Features

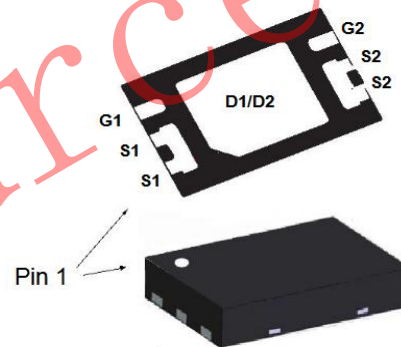
- ◆ $V_{DS} = 20V$, $I_D = 9.5A$
@ $V_{GS} = 4.5V$ $R_{DS(ON)}(Typ.) = 7.8m\Omega$
@ $V_{GS} = 4.2V$ $R_{DS(ON)}(Typ.) = 8m\Omega$
@ $V_{GS} = 3.8V$ $R_{DS(ON)}(Typ.) = 8.3m\Omega$
@ $V_{GS} = 2.5V$ $R_{DS(ON)}(Typ.) = 11m\Omega$
ESD Rating: 2000V HBM
- ◆ High power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface mount package



Product code

Date code

Marking Description



DFN2x3-6L Pin definition and Top / Bottom View

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	9.5	A
Drain Current-Pulsed (Note 1)	I_{DM}	30	A
Maximum Power Dissipation	P_D	0.98	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ C$



Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V, V _{DS} =0V	-	-	±10	μA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.45	0.7	0.95	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =5.5A	6	7.8	9	mΩ
		V _{GS} =4.2V, I _D =5.5A	6.5	8	9.5	mΩ
		V _{GS} =3.8V, I _D =5.0A	7	8.3	10	mΩ
		V _{GS} =2.5V, I _D =5.0A	9	11	12	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =5A	-	20	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{iss}	V _{DS} =10V, V _{GS} =0V, F=1.0MHz	-	1647	-	PF
Output Capacitance	C _{oss}		-	170	-	PF
Reverse Transfer Capacitance	C _{rss}		-	148	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =15V, I _D =5.5A	-	10		nS
Turn-on Rise Time	t _r		-	39.5		nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =4.5V, R _{GEN} =6Ω	-	65		nS
Turn-Off Fall Time	t _f		-	30		nS
Total Gate Charge	Q _g	V _{DS} =15V, I _D =5.5A, V _{GS} =4.5V	-	22		nC
Gate-Source Charge	Q _{gs}		-	3.1	-	nC
Gate-Drain Charge	Q _{gd}		-	8.2	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _S =1A	-	-	1.2	V
Diode Forward Current (Note 2)	I _S		-	-	7	A

Notes:

- surface mounted on FR4 board, t≤10sec
- pulse test: pulse width≤300μs, duty≤2%
- guaranteed by design, not subject to production testing

Thermal Characteristics

Thermal Resistance junction-to ambient	R _{th JA}	126	°C/W
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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

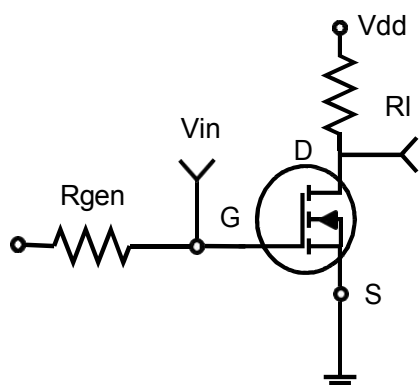


Figure 1: Switching Test Circuit

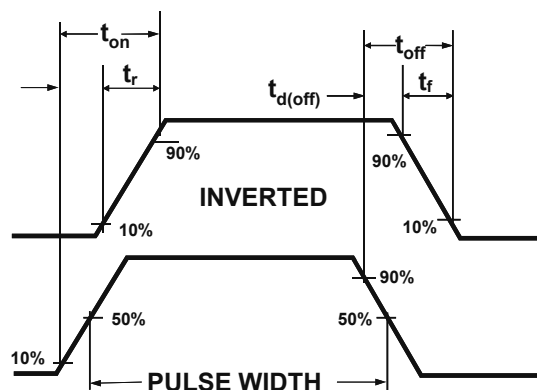


Figure 2: Switching Waveforms

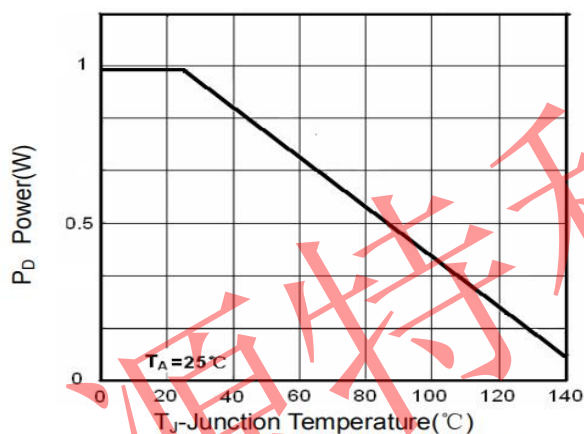


Figure 3: Power Dissipation

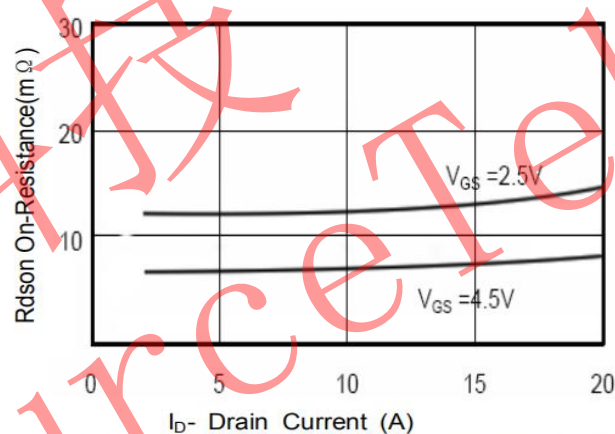


Figure 4: Drain-Source On-Resistance

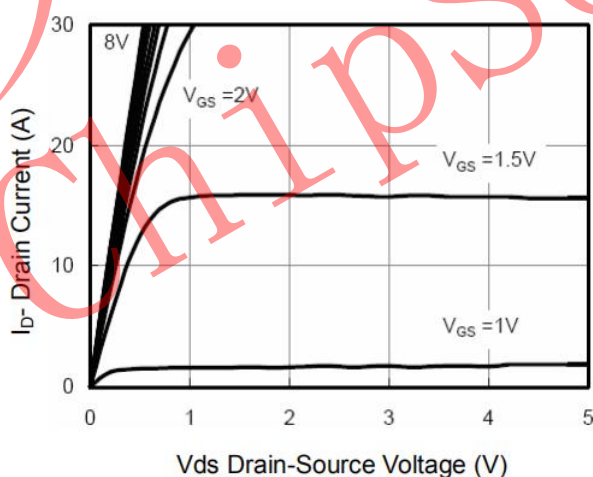


Figure 5: Output CHARACTERISTICS

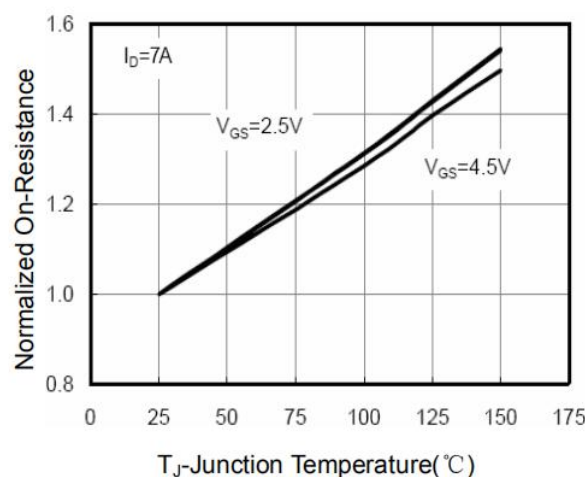


Figure 6: Drain-Source On-Resistance

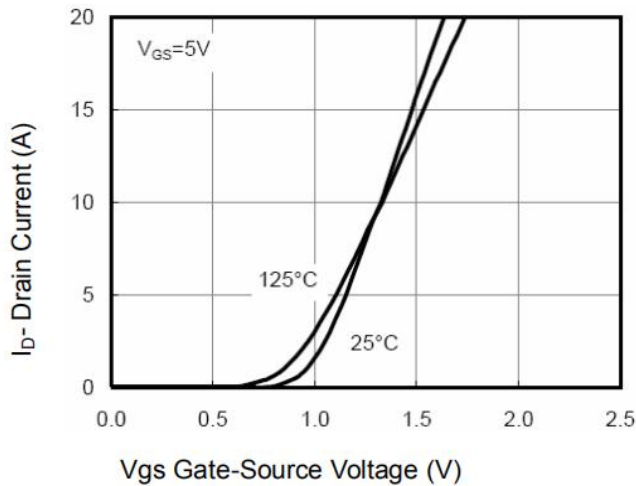


Figure 7 Transfer Characteristics

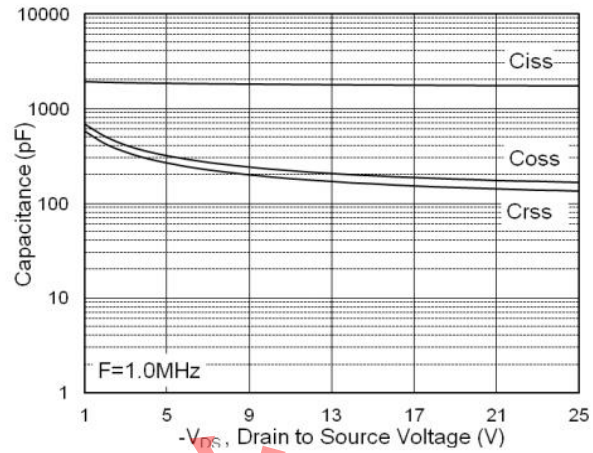


Figure 8 Capacitance vs Vds

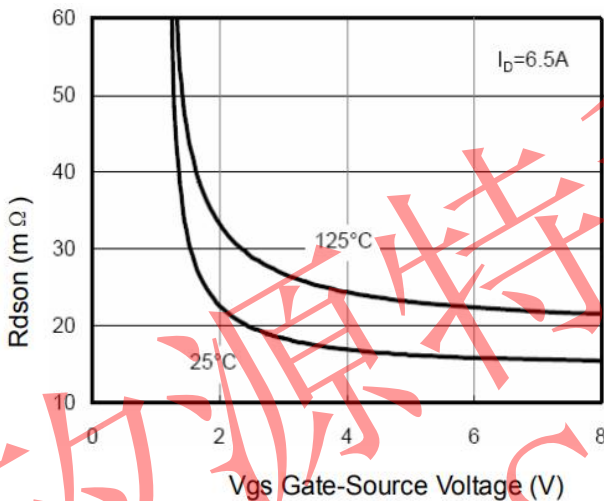


Figure 9 $R_{DS(on)}$ vs Vgs

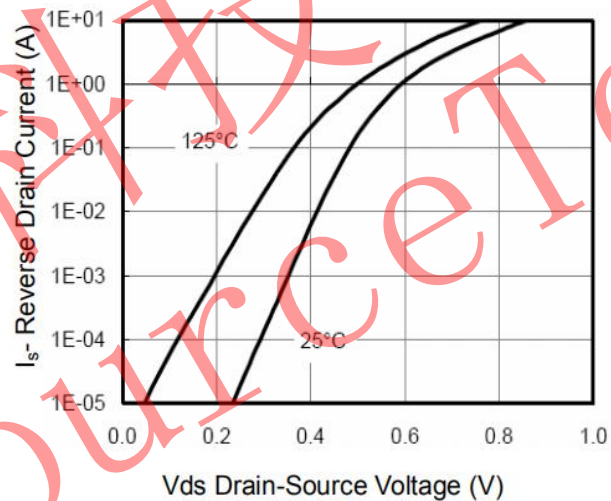


Figure 10 Capacitance vs Vds

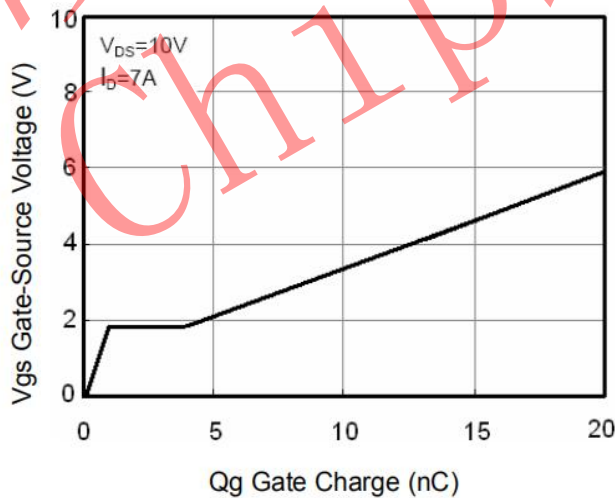


Figure 11 Gate Charge

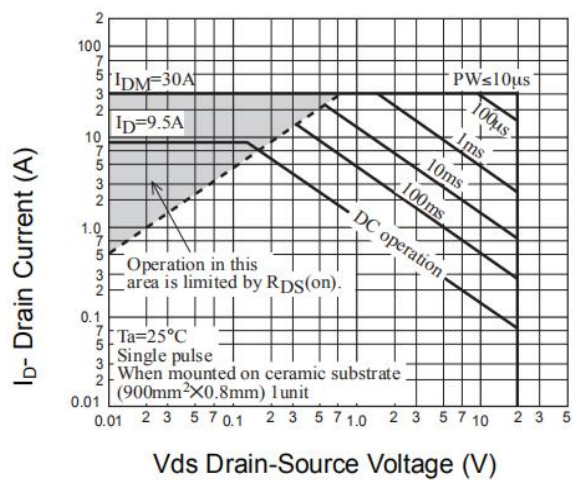
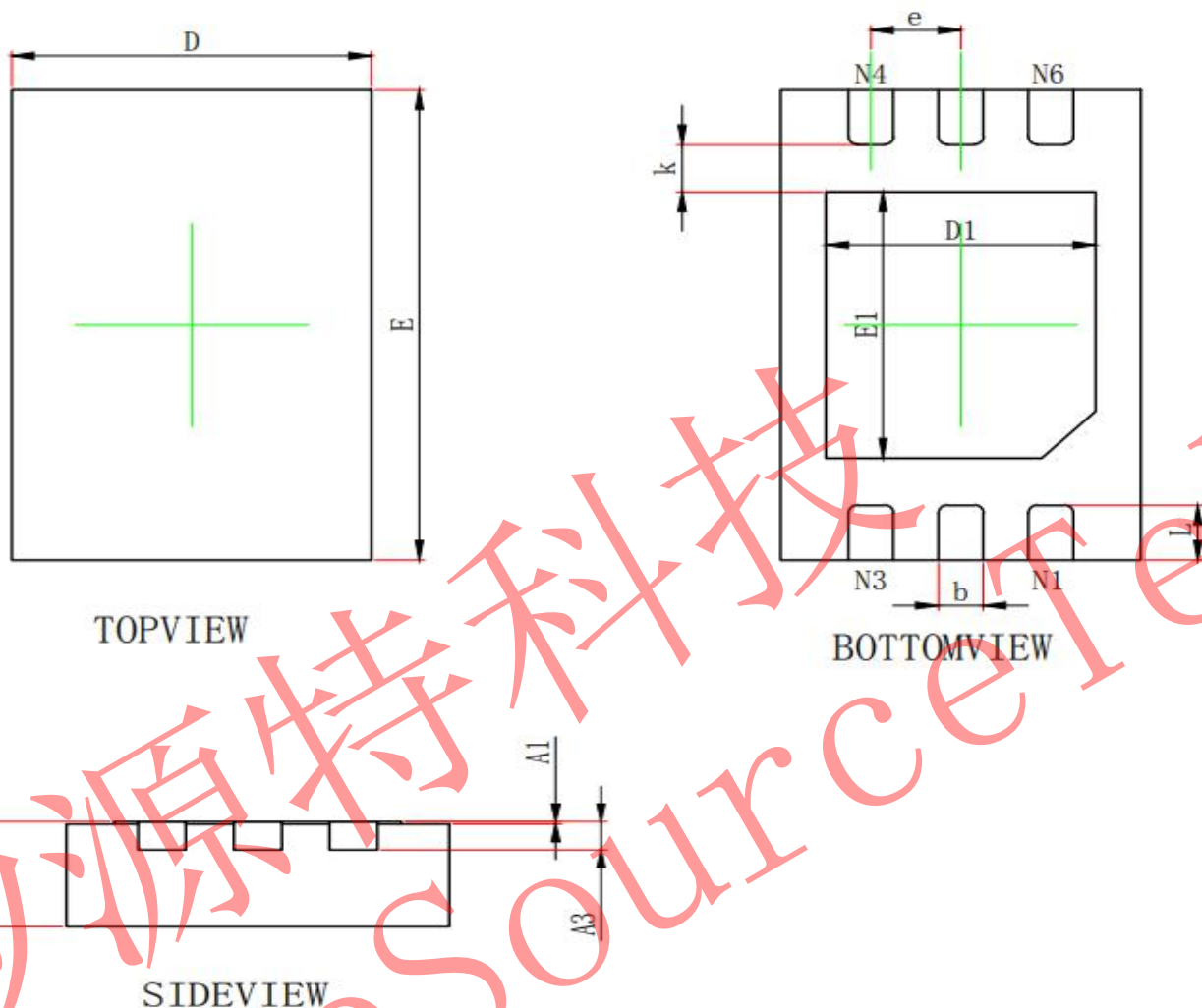


Figure 12 Safe Operation Area



DFNWB2×3-6L (P0.50T0.75) PACKAGE OUTLINED DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.950	2.050	0.077	0.081
E	2.950	3.050	0.116	0.120
D1	1.450	1.550	0.057	0.061
E1	1.650	1.750	0.065	0.069
k	0.200MIN.		0.008MIN.	
b	0.200	0.300	0.008	0.012
e	0.500TYP.		0.020TYP.	
L	0.300	0.400	0.012	0.016